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INFORMATION DISCLOSURE STATEMENT BY APPLICANT		FILING DATE: January 6, 2004	CONFIRMATION NO.: 3742
		APPLICANT: Narendra et al.	
		GROUP ART UNIT: 1755	EXAMINER: Karl E. Group
Sheet 1	of 1		

U.S. PATENT DOCUMENTS

Examiner's Initials	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or of issue of Cited Document MM-DD-YYYY
		Number	Kind Code		
<i>M</i>		*5,834,387		Divakar et al.	11-10-1998

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Examiner's Initials	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document (not necessary)	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/ Country	Number	Kind Code			
<i>M</i>		EP	1 184 355	A1	Toshiba Ceramics Co., Ltd.	03-06-2002	
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OTHER ART – NON PATENT LITERATURE DOCUMENTS

Examiner's Initials	Cite No	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue number(s), publisher, city and/or country where published.	Translation (Y/N)
<i>M</i>		H. RAUH, "Atlas for Characterization of Defects in Silicon," Wacker Siltronic AG, Burghausen, Germany, pp. 1-64, 2004.	
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<i>M</i>		NILSON et al., "Scaling wafer stresses and thermal processes to large wafers," <i>Thin Solid Films</i> 315, 1998, pp. 286-293.	
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EXAMINER <i>Karl E.</i>	DATE CONSIDERED <i>1-18-06</i>
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#EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

*a copy of this reference is not provided because a copy of this reference need not be provided as the reference is a published U.S. Patent or U.S. Patent application and the present application was filed after June 30, 2003.